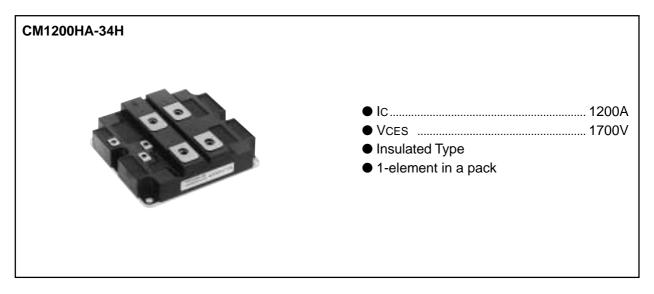
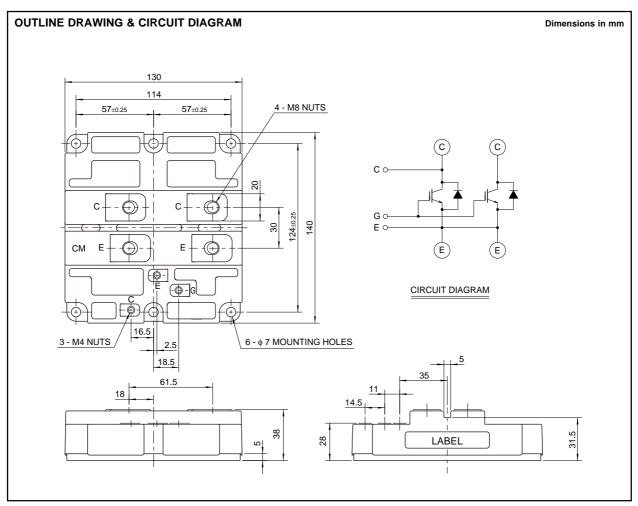
HIGH POWER SWITCHING USE INSULATED TYPE

HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Inverters, Converters, DC choppers, Induction heating, DC to DC converters.



HVIGBT MODULES (High Voltage Insulated Gate Bipolar Transistor Modules)



HIGH POWER SWITCHING USE INSULATED TYPE

HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS (Tj = 25°C)

Symbol	Item	Conditions	Ratings	Unit
VCES	Collector-emitter voltage	VGE = 0V	1700	V
VGES	Gate-emitter voltage	VCE = 0V	±20	V
Ic	Collector current	DC, Tc = 95°C	1200	Α
Ісм	Collector current	Pulse (Note 1) 2400	Α
IE (Note 2)	- Emitter current		1200	Α
IEM (Note 2)	Emiller current	Pulse (Note 1) 2400	Α
PC (Note 3)	Maximum collector dissipation	Tc = 25°C, IGBT part	13800	W
Tj	Junction temperature	_	-40 ~ + 150	°C
Tstg	Storage temperature	_	−40 ~ +125	°C
Viso	Isolation voltage	Charged part to base plate, rms, sinusoidal, AC 60Hz 1mir	4000	V
_	Mounting torque	Main terminals screw M8	6.67 ~ 13.00	N⋅m
		Mounting screw M6	2.84 ~ 6.00	N⋅m
		Auxiliary terminals screw M4	0.88 ~ 2.00	N⋅m
_	Mass	Typical value	1.5	kg

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

Symbol	Item	Conditions	Limits			Unit
		Conditions		Тур	Max	Unit
ICES	Collector cutoff current	VCE = VCES, VGE = 0V	_	_	30	mA
VGE(th)	Gate-emitter threshold voltage	IC = 120mA, VCE = 10V	4.5	5.5	6.5	V
IGES	Gate-leakage current	VGE = VGES, VCE = 0V	_	_	0.5	μΑ
VCE(sat)	Collector-emitter	Tj = 25°C	_	2.75	3.58	V
	saturation voltage	$T_j = 125$ °C IC = 1200A, VGE = 15V (Note 4)	_	3.30	_	
Cies	Input capacitance	VCE = 10V VGE = 0V	_	140	_	nF
Coes	Output capacitance		_	20.0	_	nF
Cres	Reverse transfer capacitance		_	7.6	_	nF
QG	Total gate charge	Vcc = 850V, Ic = 1200A, VGE = 15V	_	6.6	_	μC
td (on)	Turn-on delay time	Vcc = 850V, Ic = 1200A	_	_	1.20	μs
tr	Turn-on rise time	VGE1 = VGE2 = 15V	_	_	1.50	μs
td (off)	Turn-off delay time	$RG = 1.6\Omega$	_	_	2.00	μs
tf	Turn-off fall time	Resistive load switching operation	_	_	0.60	μs
VEC (Note 2)	Emitter-collector voltage	IE = 1200A, VGE = 0V	_	2.40	3.12	V
trr (Note 2)	Reverse recovery time	IE = 1200A	_	_	2.00	μs
Qrr (Note 2)	Reverse recovery charge	die / dt = -2400A / μs	_	200	_	μC
Rth(j-c)Q	Thermal resistance	Junction to case, IGBT part	_	_	0.009	K/W
Rth(j-c)R		Junction to case, FWDi part		_	0.028	K/W
Rth(c-f)	Contact thermal resistance	Case to fin, conductive grease applied	_	0.008	_	K/W

- Note 1. Pulse width and repetition rate should be such that the device junction temp. (Tj) does not exceed T_{jmax} rating.

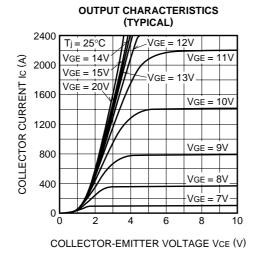
 2. IE, VEC, trr, Qrr & die/dt represent characteristics of the anti-parallel, emitter to collector free-wheel diode.

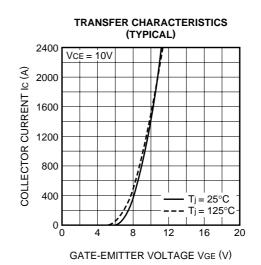
 - Junction temperature (Tj) should not increase beyond 150°C.
 Pulse width and repetition rate should be such as to cause negligible temperature rise.



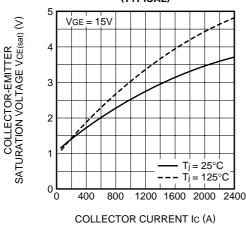
HIGH POWER SWITCHING USE INSULATED TYPE

PERFORMANCE CURVES

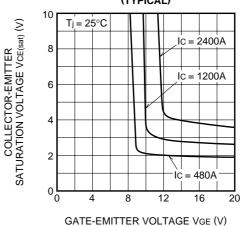




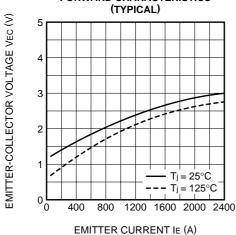
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



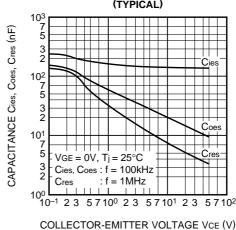
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE **FORWARD CHARACTERISTICS** (TYPICAL)



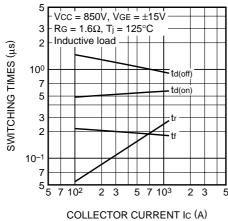
CAPACITANCE CHARACTERISTICS (TYPICAL)



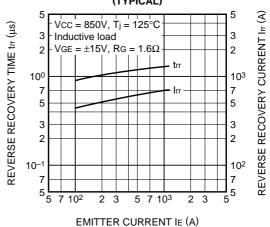
HIGH POWER SWITCHING USE INSULATED TYPE

HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

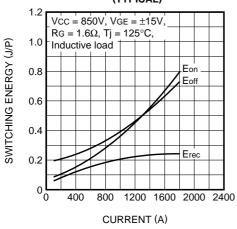




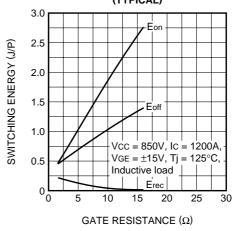
REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



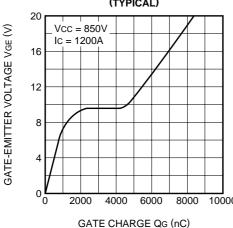
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



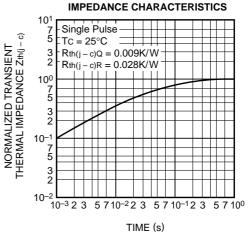
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



GATE CHARGE CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL





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